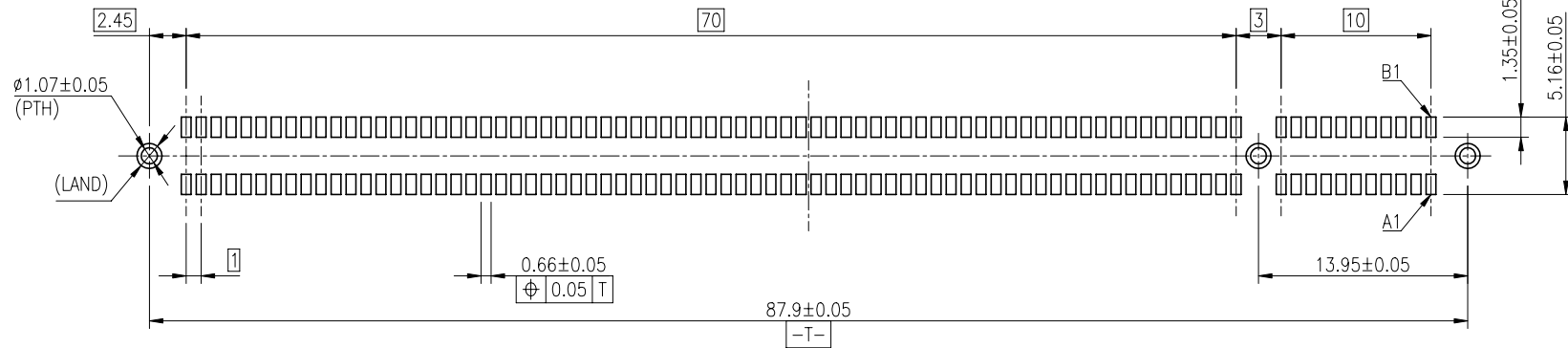


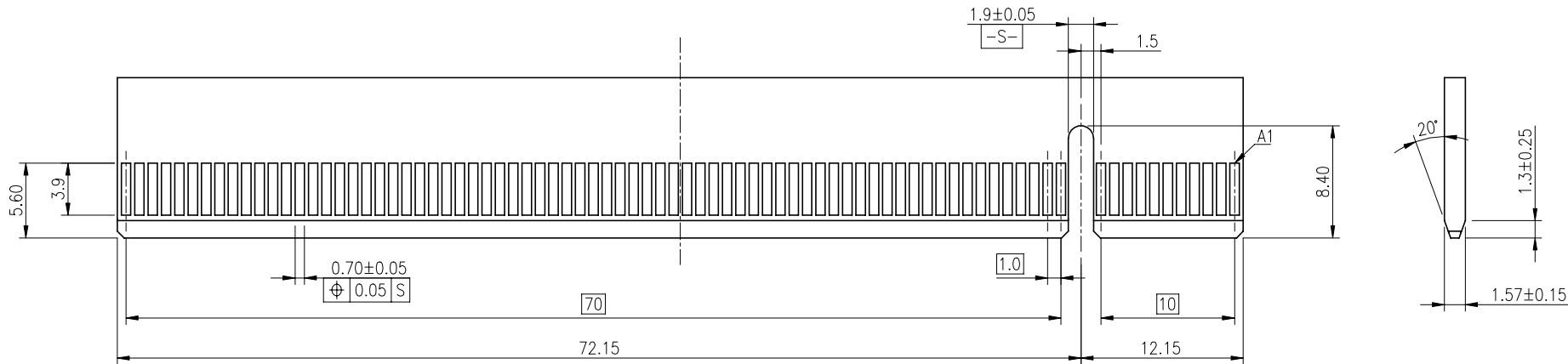
- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
 - CONTACT: COPPER ALLOY
 - FIT NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - GOLD PLATING ON CONTACT AREA.
 - 100~200u" MATTE TIN PLATING ON SOLDER TAILS.
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - FIT NAIL:
 - 100~200u" MATTE TIN PLATING ON SOLDER TAILS.
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - REFLOW SOLDER CAPABLE TO 260°C ,PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-52701-XXXX-XXX
 - PACKAGE PLS. REFER TO 50765-164TRAY-001
 - PART NUMBER

52701-XXX X X-XXX
 NO OF CKT 164.CKT TYPE 001:NONE
 PACKING 2:TRAY PLATING P: 10u" GOLD PLATING

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Liang, Chen Huan	DATE 22/12/30	
	CHECKED BY Lee, I Hung	DATE 22/12/30	
	APPROVED BY Lee, I Hung	DATE 22/12/30	UNITS mm
	SCALE 2 : 1	SHEET NO. 1 OF 2	SIZE A4
			DWG NO. 52701-XXXX-XXX
			PART NO. SEE NOTES



RECOMMENDED P.C.B. LAYOUT



RECOMMENDED P.C.B. CARD LAYOUT

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Liang, Chen Huan	DATE 22'/12/30	
	CHECKED BY Lee, I Hung	DATE 22'/12/30	
	APPROVED BY Lee, I Hung	DATE 22'/12/30	SIZE A4
	UNITS mm		DWG NO. 52701-XXXXX-XXX
	SCALE 2 : 1	SHEET NO. 2 OF 2	REV B
			PART NO. SEE NOTES